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(54) **SCALABLE COOLING ARCHITECTURE
FOR LIQUID AND AIR COOLING**

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(57) **ABSTRACT**

Multiple systems for providing liquid and air cooling for IT components is disclosed. The system includes a first module with at least one dry cooler that supplies liquid cooling to at least one liquid heat exchange device. The system also includes a second module with a first chamber that has a filter that accepts air from an outside source, a second chamber with at least one fan that moves the filtered air to cool one or more IT units resulting in heated air; and a third chamber that exhausts the heated air to the outside. A liquid heat exchange device provides liquid cooling to the one or more IT units.

